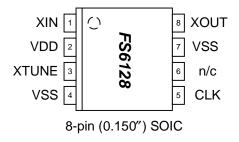


## 1.0 Features

- Phase-locked loop (PLL) device synthesizes output clock frequency from crystal oscillator or external reference clock
- On-chip tunable voltage-controlled crystal oscillator (VCXO) allows precise system frequency tuning
- Typically used for generation of MPEG-2 decoder clock
- 3.3V supply voltage
- Small circuit board footprint (8-pin 0.150" SOIC)
- Custom frequency selections available contact your local AMI Sales Representative for more information

### Figure 1: Pin Configuration



## 2.0 Description

The FS6128 is a monolithic CMOS clock generator IC designed to minimize cost and component count in digital video/audio systems.

At the core of the FS6128 is circuitry that implements a voltage-controlled crystal oscillator when an external resonator (nominally 13.5MHz) is attached. The VCXO allows device frequencies to be precisely adjusted for use in systems that have frequency matching requirements, such as digital satellite receivers.

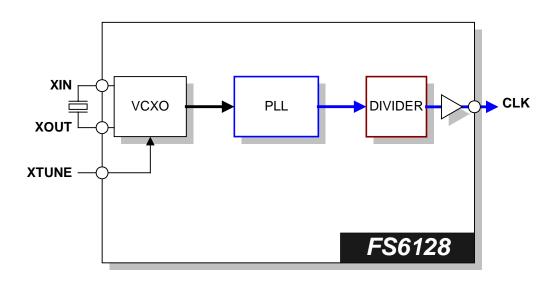
A high-resolution phase-locked loop generates an output clock (CLK) through a post-divider. The CLK frequency is ratiometrically derived from the VCXO frequency. The locking of the CLK frequency to other system reference frequencies can eliminate unpredictable artifacts in video systems and reduce electromagnetic interference (EMI) due to frequency harmonic stacking.

### **Table 1: Crystal / Output Frequencies**

DEVICE	f <sub>xin</sub> (MHz)	CLK (MHz)	XTUNE Range	
FS6128-01	13.5	27	0-2 V	

NOTE: Contact AMI for custom PLL frequencies

### Figure 2: Block Diagram





### Table 2: Pin Descriptions

Key: AI = Analog Input; AO = Analog Output; DI = Digital Input; DI<sup>U</sup> = Input with Internal Pull-Up; DI<sub>D</sub> = Input with Internal Pull-Down; DIO = Digital Input/Output; DI-3 = Three-Level Digital Input, DO = Digital Output; P = Power/Ground; # = Active Low pin

PIN	TYPE	NAME	DESCRIPTION
1	AI	XIN	VCXO Feedback
2	Р	VDD	Power Supply (+3.3V)
3	AI	XTUNE	VCXO Tune
4	Р	VSS	Ground
5	DO	CLK	Clock Output
6	-	n/c	No Connection
7	DO	VSS	Ground
8	AO	XOUT	VCXO Drive

## 3.0 Functional Block Description

### 3.1 Phase-Locked Loop (PLL)

The on-chip PLL is a standard frequency- and phaselocked loop architecture. The PLL multiplies the reference oscillator to the desired frequency by a ratio of integers. The frequency multiplication is exact with a zero synthesis error.

### 3.2 Voltage-Controlled Crystal Oscillator (VCXO)

The VCXO provides a tunable, low-jitter frequency reference for the rest of the FS6128 system components. Loading capacitance for the crystal is internal to the FS6128. No external components (other than the resonator itself) are required for operation of the VCXO.

Continuous fine-tuning of the VCXO frequency is accomplished by varying the voltage on the XTUNE pin. The value of this voltage controls the effective capacitance presented by the VCXO to the crystal.

When using a crystal with a VCXO, it is important that the crystal load capacitance (as specified in Table 4: Operating Conditions be matched to the load capacitance as presented by the VCXO. The crystal must be specified with the correct load capacitance to obtain the maximum tuning range. The oscillator operates the crystal resonator in the parallel-resonant mode. Crystal warping, or the "pulling" of the crystal oscillation frequency, is accomplished by altering the effective load capacitance presented to the crystal by the oscillator circuit. The actual amount that changing the load capacitance alters the oscillator frequency will be dependent on the characteristics of the crystal as well as the oscillator circuit itself.

Specifically, the motional capacitance of the crystal (usually referred to by crystal manufacturers as  $C_1$ ), the static capacitance of the crystal ( $C_0$ ), and the load capacitance ( $C_L$ ) of the oscillator determine the warping capability of the crystal in the oscillator circuit.

A simple formula to obtain the warping capability of a crystal oscillator is:

$$\Delta f(ppm) = \frac{C_1 \times (C_{L2} - C_{L1}) \times 10^6}{2 \times (C_0 + C_{L2}) \times (C_0 + C_{L1})}$$

where  $C_{\text{L1}}$  and  $C_{\text{L2}}$  are the two extremes of the applied load capacitance.

EXAMPLE: A crystal with the following parameters is used. With  $C_1 = 0.02pF$ ,  $C_0 = 5pF$ ,  $C_{L1} = 13pF$ , and  $C_{L2} = 35pF$ , the coarse tuning range is

$$\Delta f = \frac{0.02 \times (35 - 13) \times 10^6}{2 \times (5 + 35) \times (5 + 13)} \approx 305 \, ppm \,.$$



## 4.0 **Electrical Specifications**

### **Table 3: Absolute Maximum Ratings**

Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. These conditions represent a stress rating only, and functional operation of the device at these or any other conditions above the operational limits noted in this specification is not implied. Exposure to maximum rating conditions for extended conditions may affect device performance, functionality, and reliability.

PARAMETER	SYMBOL	MIN.	MAX.	UNITS
Supply Voltage (V <sub>SS</sub> = ground)	V <sub>DD</sub>	V <sub>SS</sub> -0.5	7	V
Input Voltage, dc	VI	V <sub>SS</sub> -0.5	V <sub>DD</sub> +0.5	V
Output Voltage, dc	Vo	V <sub>SS</sub> -0.5	V <sub>DD</sub> +0.5	V
Input Clamp Current, dc ( $V_1 < 0$ or $V_1 > V_{DD}$ )	I <sub>IK</sub>	-50	50	mA
Output Clamp Current, dc (V <sub>I</sub> < 0 or V <sub>I</sub> > V <sub>DD</sub> )	I <sub>ок</sub>	-50	50	mA
Storage Temperature Range (non-condensing)	Ts	-65	150	°C
Ambient Temperature Range, Under Bias	T <sub>A</sub>	-55	125	°C
Junction Temperature	TJ		125	°C
Lead Temperature (soldering, 10s)			260	°C
Input Static Discharge Voltage Protection (MIL-STD 883E, Method 3015.7)			2	kV



#### **CAUTION: ELECTROSTATIC SENSITIVE DEVICE**

Permanent damage resulting in a loss of functionality or performance may occur if this device is subjected to a high-energy electrostatic discharge.

## **Table 4: Operating Conditions**

PARAMETER	SYMBOL	CONDITIONS/DESCRIPTION	MIN.	TYP.	MAX.	UNITS
Supply Voltage	V <sub>DD</sub>	3.3V ± 10%	3.0	3.3	3.6	V
Ambient Operating Temperature Range	T <sub>A</sub>		0		70	°C
Crystal Resonator Frequency	f <sub>XTAL</sub>	Fundamental Mode	5	13.5	18	MHz
Crystal Resonator Motional Capacitance	C <sub>1(xtal)</sub>	AT cut		25		fF
Crystal Loading Capacitance	C <sub>L(xtal)</sub>	AT cut		20		pF



## **Table 5: DC Electrical Specifications**

Unless otherwise stated,  $V_{DD}$  = 3.3V ± 10%, no load on any output, and ambient temperature range  $T_A$  = 0°C to 70°C. Parameters denoted with an asterisk (\*) represent nominal characterization data and are not production tested to any specific limits. Where given, MIN and MAX characterization data are ±3 $\sigma$ from typical. Negative currents indicate current flows out of the device.

PARAMETER	SYMBOL	CONDITIONS/DESCRIPTION		TYP.	MAX.	UNITS
Overall						
Supply Current, Dynamic, with Loaded Outputs	I <sub>DD</sub>	$f_{XTAL} = 13.5 MHz; C_L = 10 pF, V_{DD} = 3.6 V$		30		mA
Supply Current, Static	I <sub>DD</sub>	XIN = 0V, V <sub>DD</sub> = 3.6V		3		mA
Voltage Controlled Crystal Oscillator						
Crystal Loading Capacitance	$C_{\text{L(xtal)}}$	As seen by a crystal connected to XIN and XOUT (@ $V_{XTUNE} = 1V$ )		20		pF
Crystal Resonator Motional Capacitance	C <sub>1(xtal)</sub>	AT cut		25		fF
VCXO Tuning Range		$f_{XTAL} = 13.5MHz; C_{L(xtal)} = 20pF; C_{1(xtal)} = 25fF$		300		ppm
VCXO Tuning Characteristic		Note: positive change of XTUNE = positive change of VCXO frequency		150		ppm/V
Crystal Drive Level		$R_{XTAL}=20\Omega; C_L = 20pF$		200		uW
Clock Output (CLK)					L	1
High-Level Output Source Current *	I <sub>OH</sub>	V <sub>0</sub> = 2.0V		-40		mA
Low-Level Output Sink Current *	I <sub>OL</sub>	$V_{O} = 0.4V$		17		mA
Output Impadance *	Z <sub>OH</sub>	$V_{O} = 0.1 V_{DD}$ ; output driving high		25		Ω
Output Impedance *	Z <sub>OL</sub>	$V_{O} = 0.1 V_{DD}$ ; output driving low		25		52
Short Circuit Source Current *	I <sub>OSH</sub>	$V_{o} = 0V$ ; shorted for 30s, max55			mA	
Short Circuit Sink Current *	I <sub>OSL</sub>	$V_0 = 3.3V$ ; shorted for 30s, max.		55		mA



## **Table 6: AC Timing Specifications**

Unless otherwise stated,  $V_{DD}$  = 3.3V ± 10%, no load on any output, and ambient temperature range  $T_A$  = 0°C to 70°C. Parameters denoted with an asterisk ( \* ) represent nominal characterization data and are not production tested to any specific limits. Where given, MIN and MAX characterization data are ±3 $\sigma$ from typical.

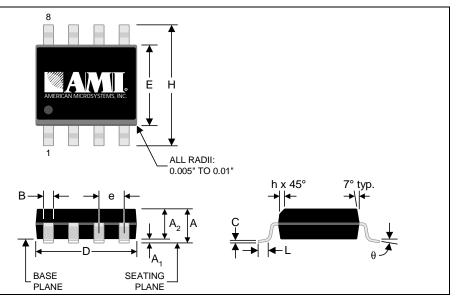
PARAMETER	SYMBOL	CONDITIONS/DESCRIPTION		TYP.	MAX.	UNITS	
Overall							
VCXO Stabilization Time *	t <sub>VCXOSTB</sub>	From power valid		10		ms	
PLL Stabilization Time *	t <sub>PLLSTB</sub>	From VCXO stable		500		us	
Synthesis Error		(unless otherwise noted in Frequency Table)			0	ppm	
Clock Output (CLK)	Clock Output (CLK)						
Duty Cycle *		Ratio of high pulse width (as measured from rising edge to next falling edge at $V_{DD}/2$ ) to one clock period	45		55	%	
Jitter, Period (peak-peak) *	$t_{j(\Delta P)}$	From rising edge to next rising edge at $V_{DD}/2$ , $C_L = 10 pF$		390		ps	
Jitter, Long Term ( $\sigma_{y}(\tau)$ ) *	t <sub>j(LT)</sub>	From 0-500 $\mu$ s at V <sub>DD</sub> /2, C <sub>L</sub> = 10pF compared to ideal clock source		155		ps	
Rise Time *	tr	$V_{\text{DD}}$ = 3.3V; $V_{\text{O}}$ = 0.3V to 3.0V; $C_{\text{L}}$ = 10pF		1.7		ns	
Fall Time *	t <sub>f</sub>	$V_{\text{DD}}$ = 3.3V; $V_{\text{O}}$ = 3.0V to 0.3V; $C_{\text{L}}$ = 10pF		1.7		ns	



## 5.0 Package Information

## Table 7: 8-pin SOIC (0.150") Package Dimensions

	DIMENSIONS						
	INC	HES	MILLIM	ETERS			
	MIN.	MAX.	MIN.	MAX.			
А	0.061	0.068	1.55	1.73			
A1	0.004	0.0098	0.102	0.249			
A2	0.055	0.061	1.40	1.55			
В	0.013	0.019	0.33	0.49			
С	0.0075	0.0098	0.191	0.249			
D	0.189	0.196	4.80	4.98			
Е	0.150	0.157	3.81	3.99			
е	0.050	BSC	1.27	BSC			
Н	0.230	0.244	5.84	6.20			
h	0.010	0.016	0.25	0.41			
L	0.016	0.035	0.41	0.89			
Θ	<b>0</b> °	8°	<b>0</b> °	<b>8</b> °			



# Table 8: 8-pin SOIC (0.150") Package Characteristics

PARAMETER	SYMBOL	CONDITIONS/DESCRIPTION	TYP.	UNITS	
Thermal Impedance, Junction to Free-Air 8-pin 0.150" SOIC	$\Theta_{JA}$	Air flow = 0 m/s	110	°C/W	
Laad Inductorias Salf	L <sub>11</sub>	Corner lead	2.0	nH	
Lead Inductance, Self		Center lead	1.6		
Lead Inductance, Mutual	L <sub>12</sub>	Any lead to any adjacent lead	0.4	nH	
Lead Capacitance, Bulk	C <sub>11</sub>	Any lead to $V_{SS}$	0.27	pF	



## 6.0 Ordering Information

### **Table 9: Device Ordering Codes**

ORDERING CODE	DEVICE NUMBER	PACKAGE TYPE	OPERATING TEMPERATURE RANGE	SHIPPING CONFIGURATION
11640-101	FS6128-01	8-pin (0.150") SOIC (Small Outline Package)	0° C to 70° C (Commercial)	Tape and Reel
11640-111	FS6128-01	8-pin (0.150") SOIC (Small Outline Package)	0° C to 70° C (Commercial)	Tubes

## 7.0 Revision Information

DATE	PAGE	DESCRIPTION
4/24/00	5, 7	Fixed formatting errors

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